



# 立体成型基板用ソルダーレジスト

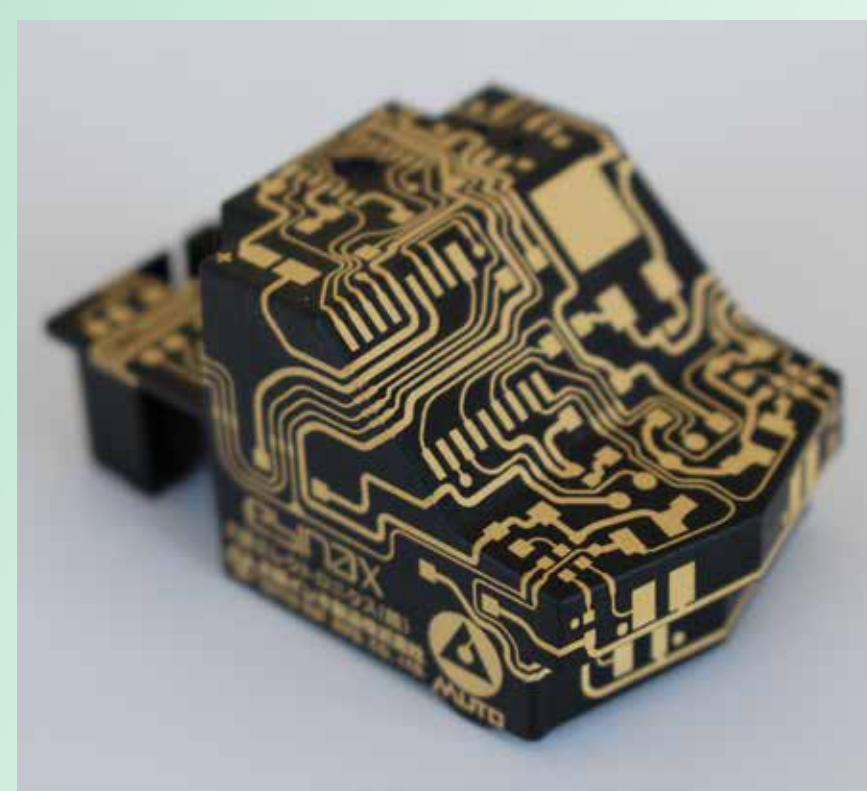
## 3D-MID用ソルダーレジスト

### ● 3D-MID基板の作成方法

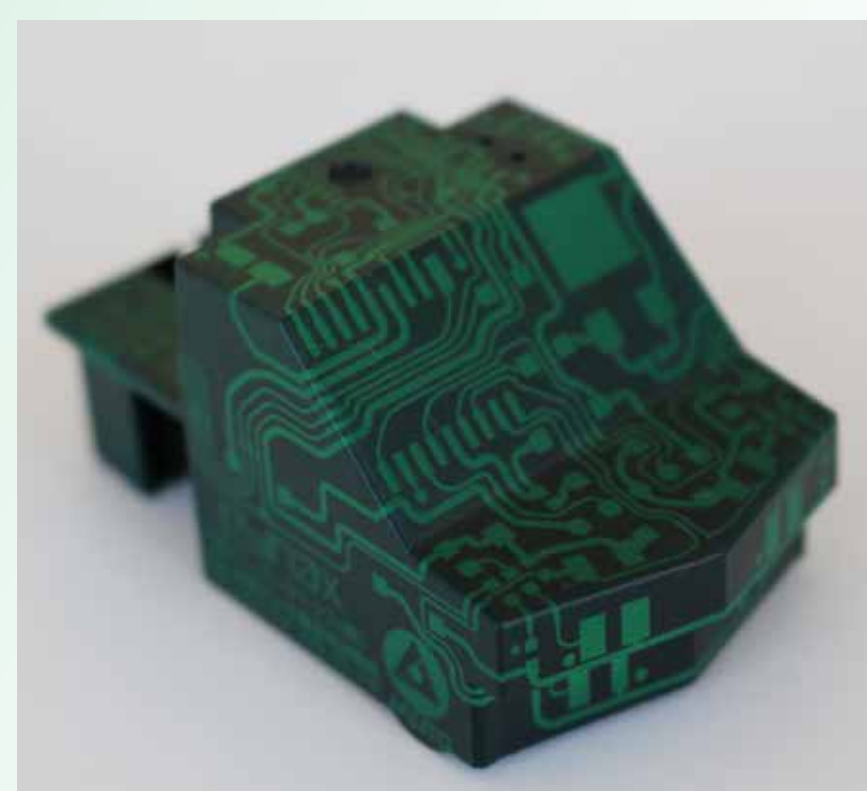
Process flow of 3D-MID



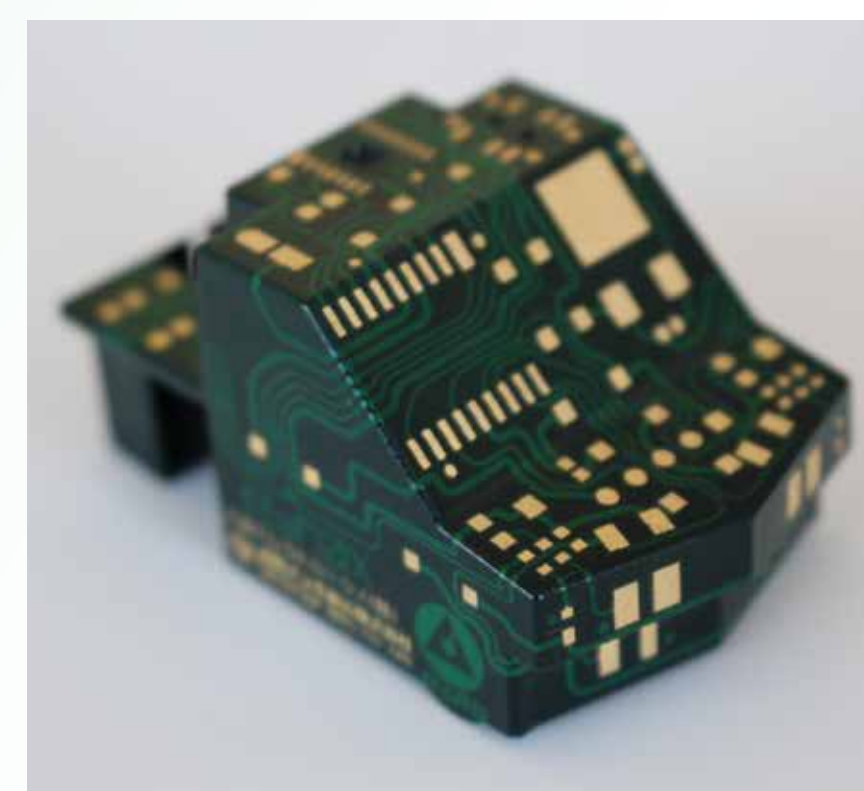
成型樹脂  
MID Resin



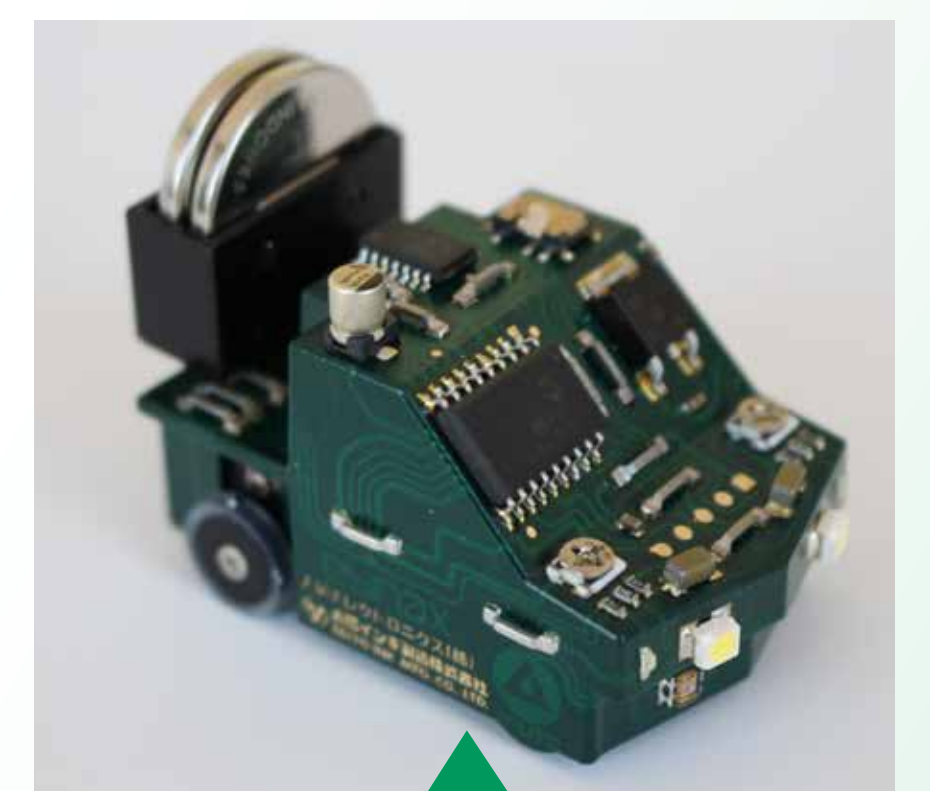
回路形成 Patterning  
+  
銅めっき Copper plating



SR 塗布  
Solder resist



レーザー開口 Leaser trimming  
+  
金めっき E' less Ni/Au Plating



部品実装  
Device mounting

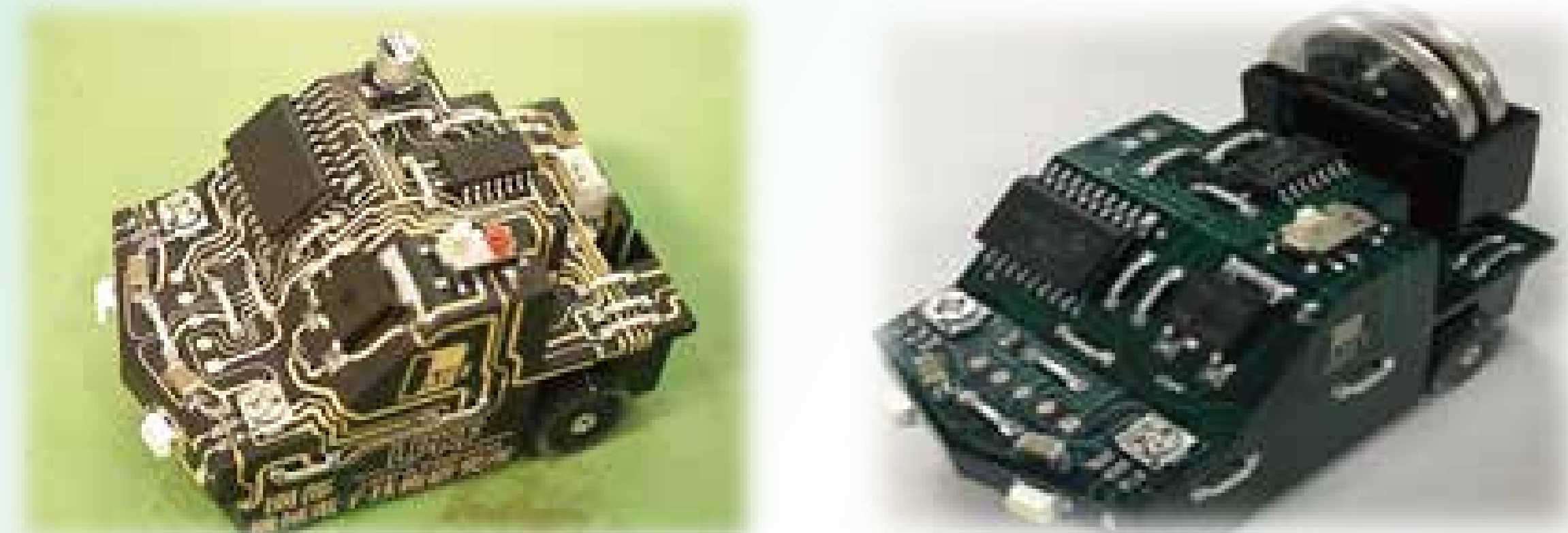
### ● ソルダーレジストの目的

Roles of Solder resist

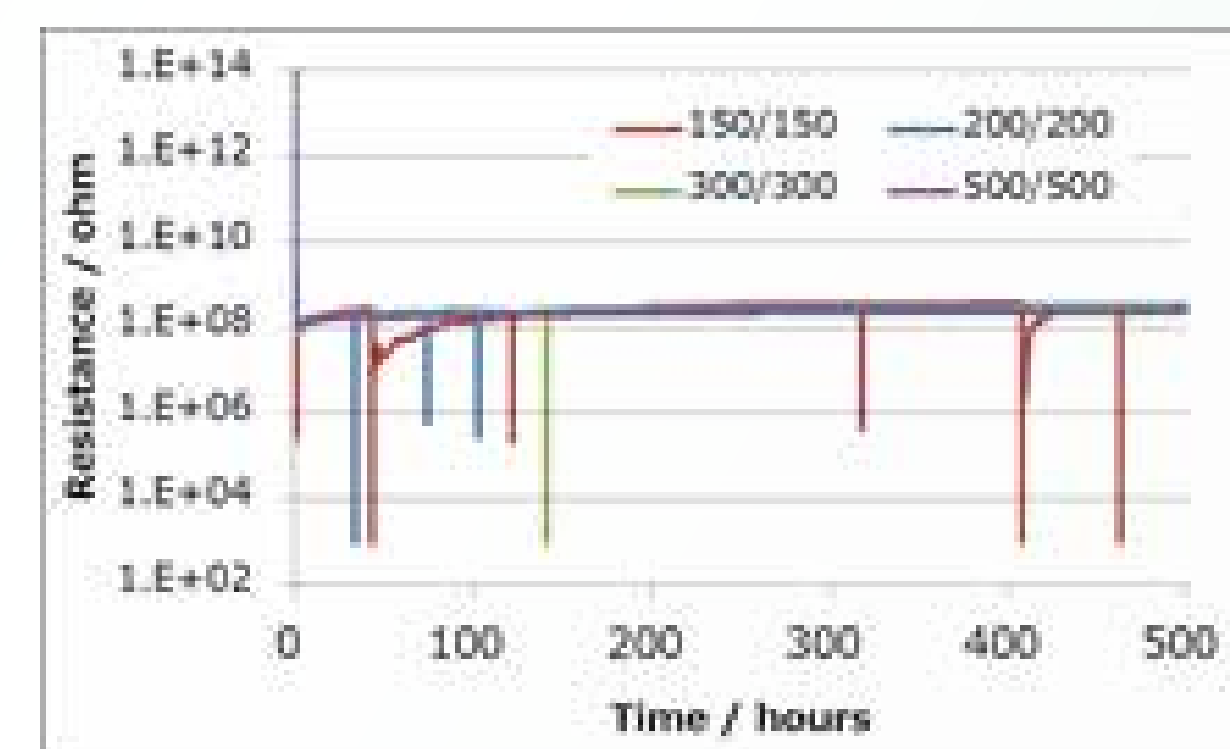
・実装時のはんだ流れ防止  
Prevention of solder outflow



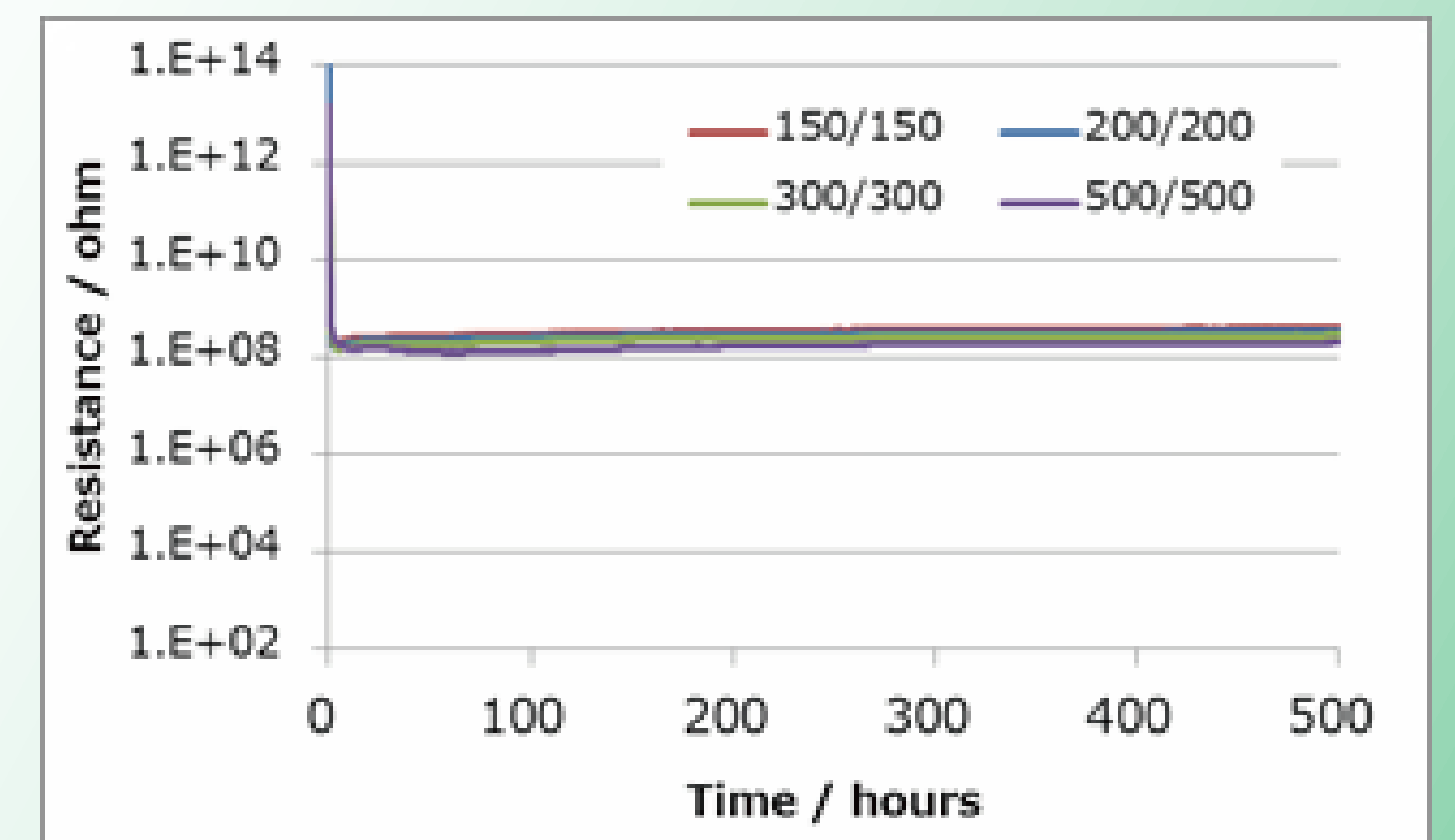
・金めっき削減によるコストダウン  
Cost reduction by reducing gold plating area



・高絶縁信頼性  
High insulation reliability



ソルダーレジスト  
があれば



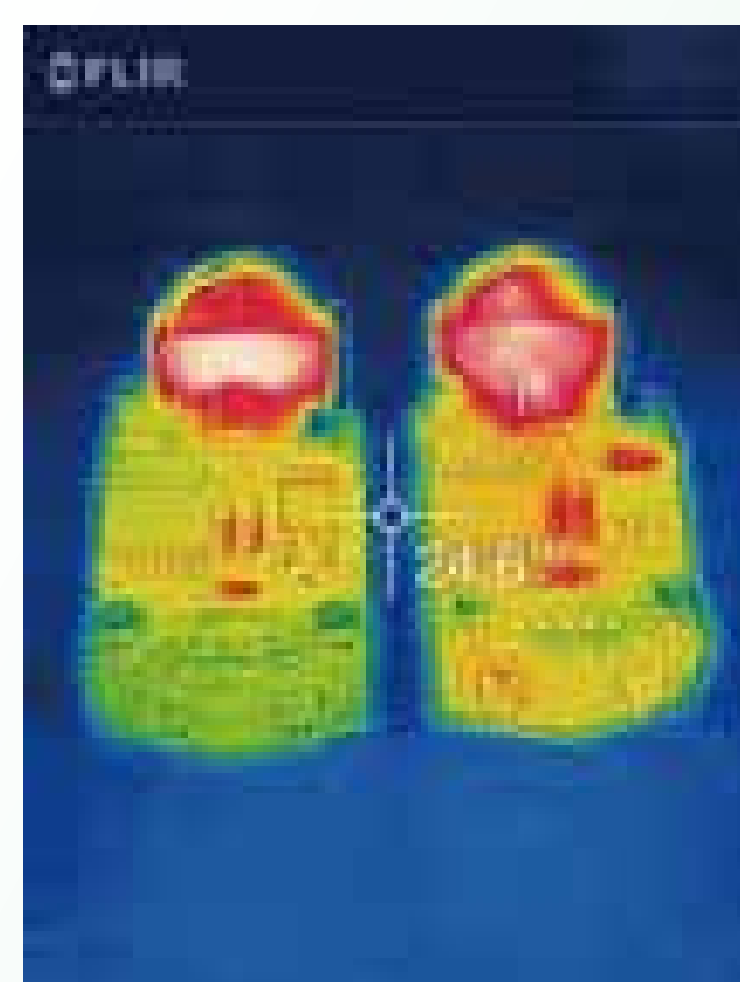
電気特性(85deg.C/85%RH/DC30V 基材:PA)  
L/S=150/150, 200/200, 300/300, 500/500 um

### ● 放熱性向上対応等各種ソルダーレジストの使用が可能

Solder-resist depending on purpose is available



高放熱ソルダーレジスト塗布  
High insulation reliability



Accutual temperature  
by thermo graph